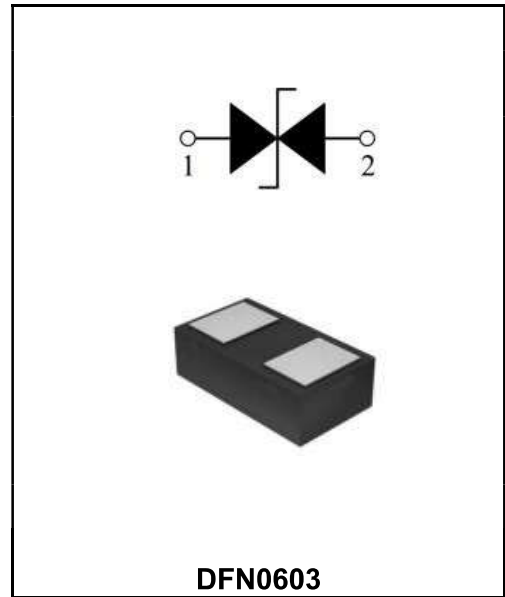


Bi-directional ESD Protection Diode
Features

- ◆Capacitance: 0.25pF(typ.)
- ◆Reverse Working Voltage: 3.3V
- ◆IEC 61000-4-2 (ESD Air): ±20KV
- ◆IEC 61000-4-2 (ESD Contact): ±20KV
- ◆IEC 61000-4-5 (Lightning 8/20μs): 9A

Application

- ◆Smart Phone and Tablet PC
- ◆TV and Set Top Box
- ◆Wearable Devices
- ◆PDA


Order Information

Part Number	Package	Marking	Size (mm)	Delivery Form	Delivery Quantity
ESD0603C3V3A	DFN0603	03	0.62x0.32x0.31	7" T&R	15000PCS/Tape

Limiting Values(TA = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	±20	kV
		IEC 61000-4-2; Air Discharge	-	±20	kV
P _{PP}	Peak Pulse Power	tP = 8/20 μs		54	W
I _{PPM}	Rated Peak Pulse Current	tP = 8/20 μs		9	A
T _A	Operating Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-55	150	°C

Electrical Characteristics(TA = 25 °C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V _{RWM}	Reverse Working Voltage	TA = 25 °C	-	-	3.3	V
V _{BR}	Breakdown Voltage	I _R = 1mA; TA = 25 °C	4	-	-	V
V _h	Holding Voltage	I _h =100mA	1.2	-	-	V
I _R	Reverse Leakage Current	V _{RWM} = 3.3V; TA = 25 °C	-	-	1	μA
V _C	Clamping Voltage	I _{PP} =9A, t _P =8/20μs	-	6	-	V
		I _{PP} =16A, t _P =10/100ns	-	6.5	-	V
R _{DYN}	Dynamtic Resistance	t _P =10/100ns, I _{PP} =8A to 16A	-	0.2	-	Ω
C _J	Junction Capacitance	V _R = 1V, f = 1 MHz	-	0.25	-	pF

Typical Characteristics

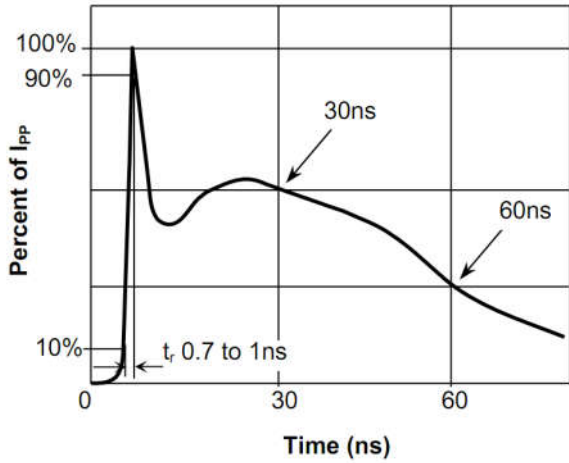


Fig.1 Pulse Waveform-ESD (IEC61000-4-2)

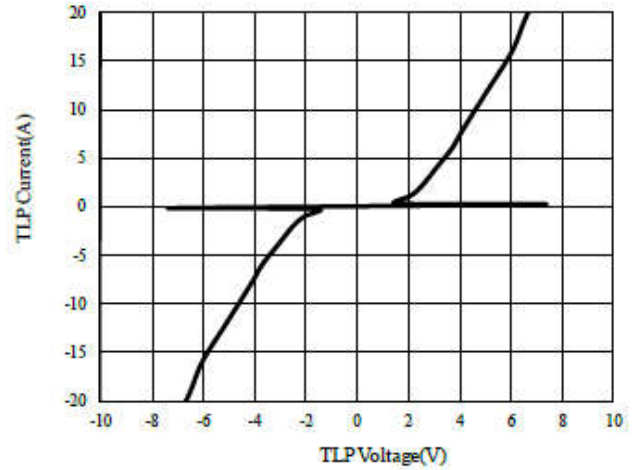


Fig.2 Transmission Line Pulse (TLP)

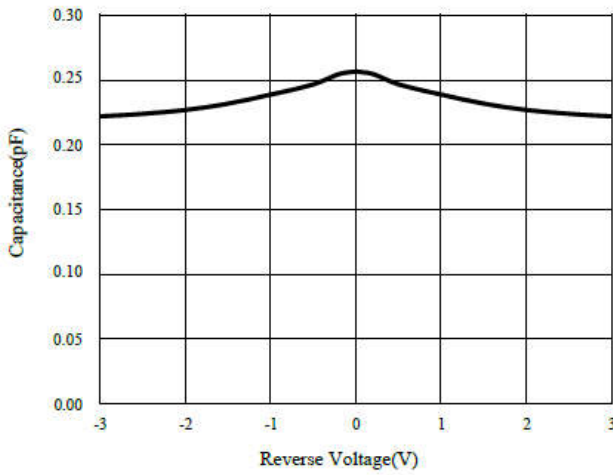


Fig.3 Capacitance VS. Voltage

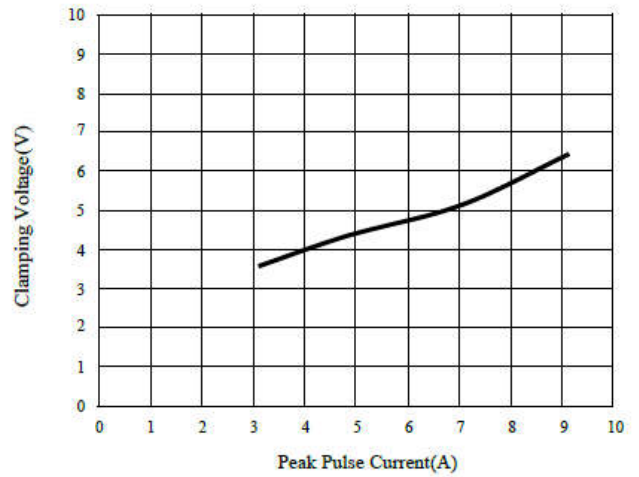


Fig.4 Clamping Voltage VS. Peak Pulse Current

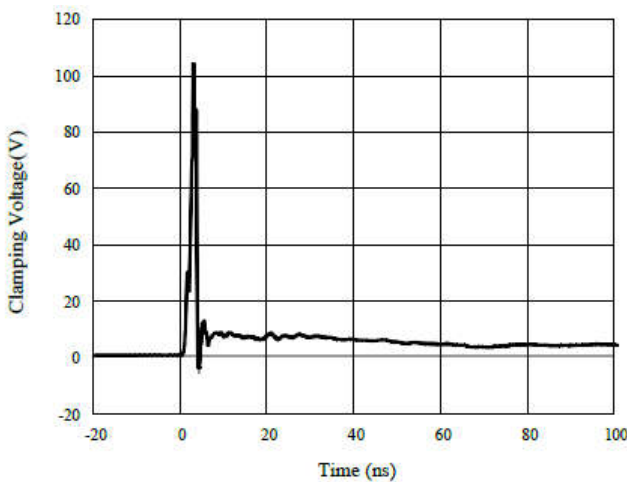


Fig.5 Clamping Voltage at IEC61000-4-2
-8kV Pulse Waveform

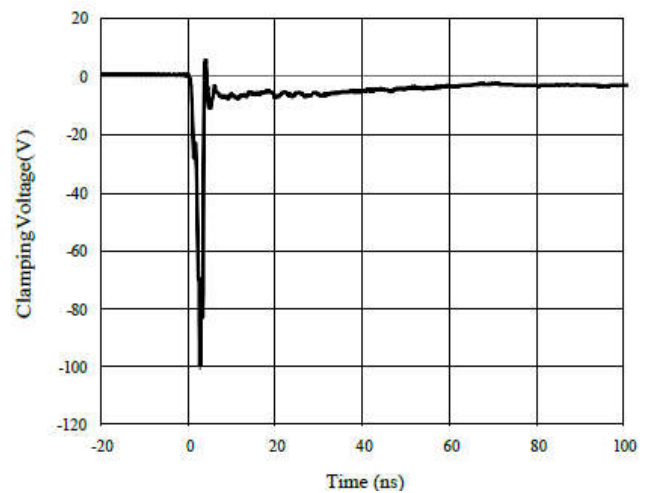
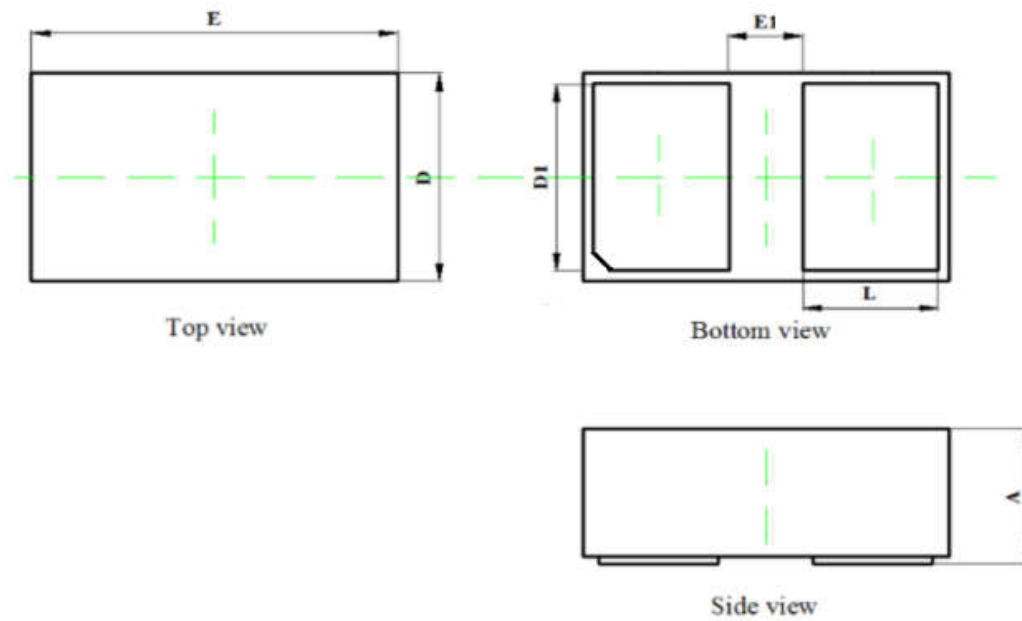
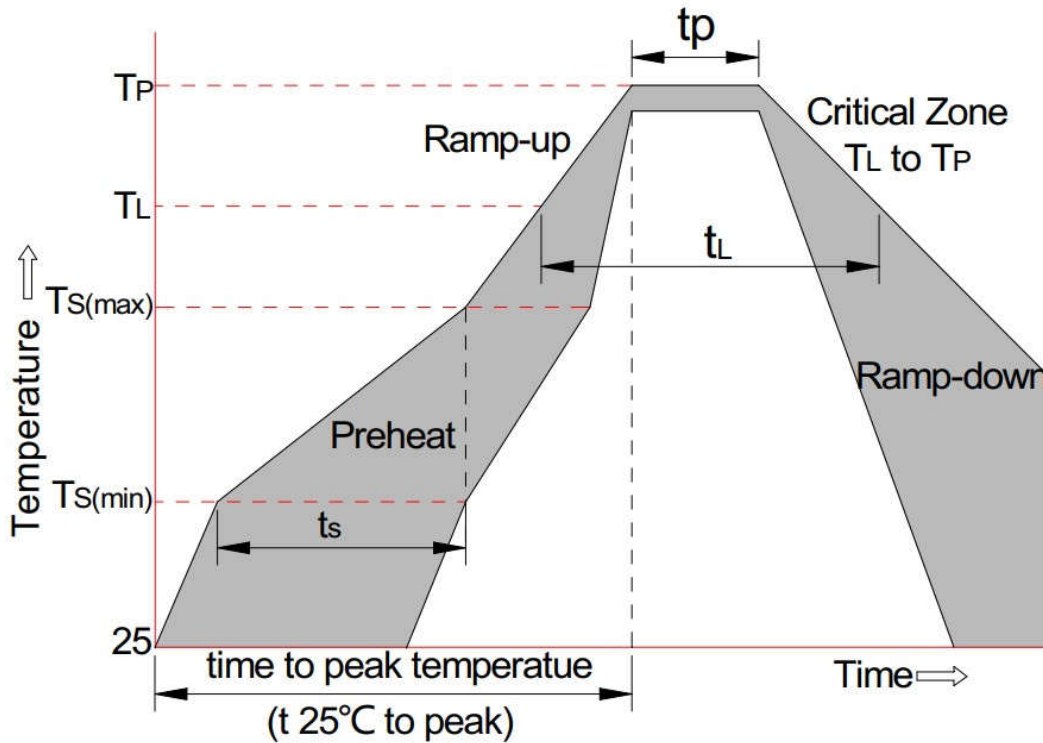


Fig.6 Clamping Voltage at IEC61000-4-2
+8kV Pulse Waveform

DFN0603 Package Outline



Symbol	Dimensions In Millimeters		
	Min	Typical	Max
A	0.28	0.31	0.34
D	0.29	0.32	0.35
E	0.59	0.62	0.65
D1	0.23	0.26	0.29
E1	0.15	0.18	0.21
L	0.16	0.19	0.22



Reflow Condition		Pb-Free Assembly
Pre-heat	-Temperature Min ($T_s(min)$)	+150°C
	-Temperature Max($T_s(max)$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_s(max)$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
xTime 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C